

THROUGH-TYPE FURNACE FOR SUBSTRATES TO BE FITTED WITH COMPONENTS AND
DIE BONDER

ABSTRACT

A through-type furnace for substrates (3) comprises a furnace (1) with a channel (2) and a transport system for the transport of the substrates (3) through the channel (2). The channel (2) is bounded by a base (4), a front side wall (5), a rear side wall (6) and a top part (7). The base (4) contains a plurality of first holes (8) which are connectable to a protective gas source (9) so that protective gas can be supplied during operation. The front side wall (5) of the channel (2) comprises a longitudinal slit (11) which extends parallel to the passage direction (10) and which is bounded by a bottom edge (12) and an upper edge (13). The transport system comprises at least one clamp (15) for transporting the substrates (3) through the channel (2). The clamp (15) is movable back and forth along the longitudinal slit (11) of the channel (2). Such a through-type furnace is in particular suitable for use in a soft solder die bonder.

(Fig. 1)